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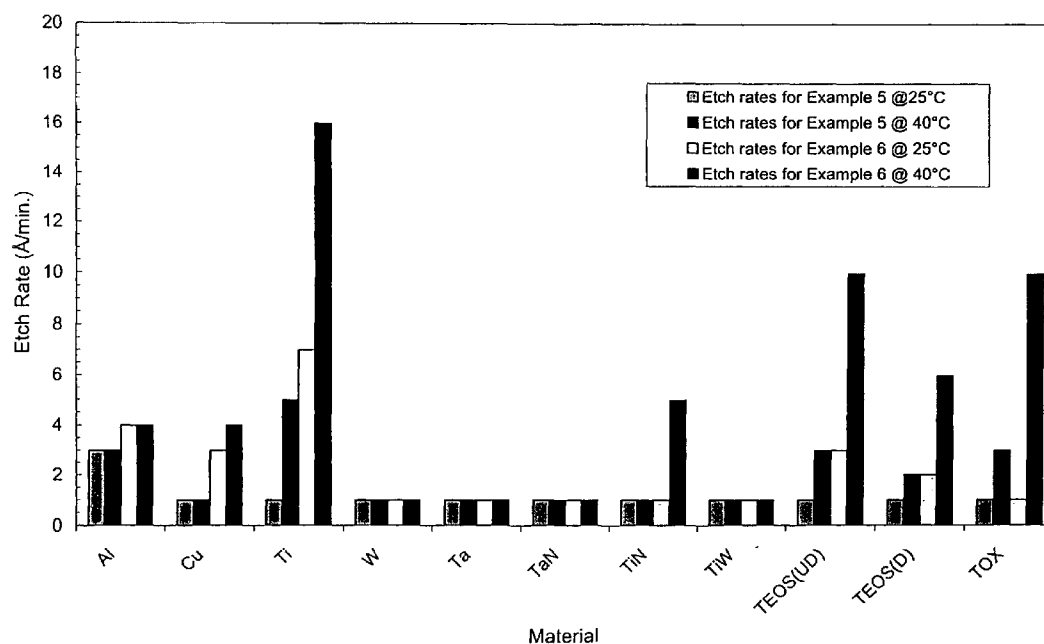
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(54) Title: AQUEOUS BUFFERED FLUORIDE-CONTAINING ETCH RESIDUE REMOVERS AND CLEANERS



(57) Abstract: The invention relates to aqueous, buffered, fluoride containing compositions having a pH of greater than 7.0 to about 11.0. The buffered compositions have an extended worklife because pH dependent attributes such as oxide and metal etch rates are stable so long as the pH remains stable.

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